

**PCN19001 【 TO-92 package of plating process  
changed from hang plating to solder dipping 】**  
**Comparison Report**

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Approved by: Jojo Zhang  
Issued date at:2018.9.26  
Version for:A

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**Customer Feedback/Approval Form**

Form provided by ZVEI - Revision 3.0.0

<b>Title of PCN:</b>			
TO-92 package of plating process changed from hang plating to solder dipping			
<b>Customer PCN No.</b>		<b>Supplier PCN No.</b>	PCN19001
<b>Please check the appropriate box below:</b>			

<input type="checkbox"/>	<b>1. Feedback</b>	<b>date:</b>	
<input type="checkbox"/>	We agree with this proposed change for the parts as listed in chapter '11. Affected parts'. Approval letter will be sent in written form.		
<input type="checkbox"/>	We agree with this proposed change schedule and will start with the PCN process. Approval letter will be sent in written form after evaluation.		
<input type="checkbox"/>	<b>We disapprove because:</b>		
<input type="checkbox"/>			
<input type="checkbox"/>	<b>Remark:</b>		
<input type="checkbox"/>			

<input type="checkbox"/>	<b>2. Feedback</b>	<b>date:</b>	
<input type="checkbox"/>	We acknowledge qualification / validation as assigned in chapter 8 of the PCN.		
<input type="checkbox"/>	<b>We need more information:</b>		
<input type="checkbox"/>			
<input type="checkbox"/>	<b>We need the following samples:</b>		
<input type="checkbox"/>			
<input type="checkbox"/>	<b>Estimated closing date for PCN:</b>		
<input type="checkbox"/>			

<input type="checkbox"/>	<b>Final Feedback/Approval</b>	<b>date:</b>	
<input type="checkbox"/>			

<b>Sender:</b>	
<b>Company:</b>	

<b>Name:</b>	
<b>Address/Location:</b>	
<b>Signature:</b>	
<b>Date:</b>	

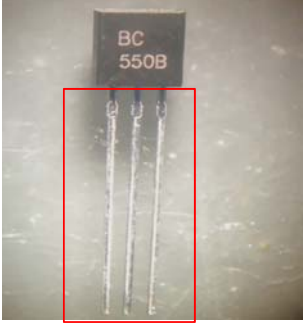
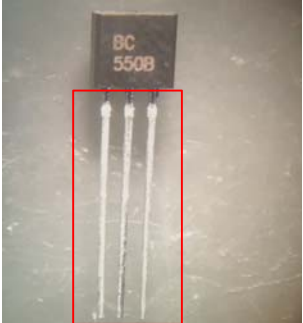
<b>Please return to: [your Sales partner]</b>	
<b>Name:</b>	
<b>Address/Location:</b>	
<b>Phone:</b>	
<b>Fax:</b>	
<b>Email:</b>	





## Comparison Report



**External marking summary:**

Before Hang plating process	After Dip soldering process	Result
		<p>Dip soldering is relatively bright.</p>

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## Comparison Report

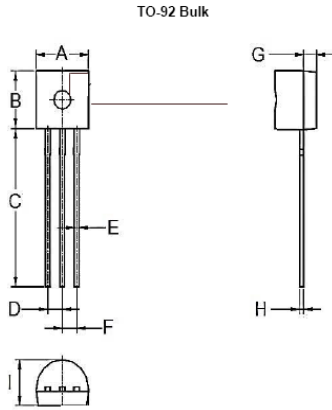
### Process Comparison

	Before Hang plating process	After Dip soldering process	Result																																																												
The production process	Die sawing → Die Bonding → Wire bonding → Molding → Curing → Trimming → Cutting → <u>Electroplating</u> → Marking → Trimming → Testing & Taping twice	Die sawing → Die Bonding → Wire bonding → Molding → Curing → Trimming → Cutting → <u>Dip soldering</u> → Marking → Trimming → Testing & Taping twice	Different plating method: a. The method of hang plating is immersed in the whole, and the Soldering time is 25±5min. b. the method of dip soldering is soaked the pins, and the level of the flux is closed to the product's plastics case, and the soaking time is 4 ±1 seconds.																																																												
Plating technology	<table border="1" style="width: 100%; border-collapse: collapse; text-align: center;"> <tr><td>1</td><td>2</td><td>3</td><td>4</td><td>5</td></tr> <tr><td>Acid cleaning</td><td>Cleaning</td><td>Electrolyte</td><td>Cleaning</td><td>oxalate</td></tr> <tr><td>6</td><td>7</td><td>8</td><td>9</td><td>10</td></tr> <tr><td>1# Cleaning</td><td>2# Cleaning</td><td>3# Cleaning</td><td>Pre-plating</td><td>Bright tin</td></tr> <tr><td>11</td><td>12</td><td>13</td><td>14</td><td>15</td></tr> <tr><td>1# Cleaning</td><td>2# Cleaning</td><td>neutraliz</td><td>Cleaning</td><td>Hot water</td></tr> <tr><td>16</td><td>17</td><td>18</td><td></td><td></td></tr> <tr><td>Feeding</td><td>solder stripping</td><td>Cleaning</td><td></td><td></td></tr> </table>	1		2	3	4	5	Acid cleaning	Cleaning	Electrolyte	Cleaning	oxalate	6	7	8	9	10	1# Cleaning	2# Cleaning	3# Cleaning	Pre-plating	Bright tin	11	12	13	14	15	1# Cleaning	2# Cleaning	neutraliz	Cleaning	Hot water	16	17	18			Feeding	solder stripping	Cleaning			<table border="1" style="width: 100%; border-collapse: collapse; text-align: center;"> <tr><td>1</td><td>2</td><td>3</td><td>4</td><td>5</td></tr> <tr><td>Soaking flux</td><td>Pre-temperature</td><td>dip soldering</td><td>ultrasonic cleaning</td><td>1# washing</td></tr> <tr><td>6</td><td>7</td><td>8</td><td></td><td></td></tr> <tr><td>2# washing</td><td>Hot water washing</td><td>Drying</td><td></td><td></td></tr> </table>	1	2	3	4	5	Soaking flux	Pre-temperature	dip soldering	ultrasonic cleaning	1# washing	6	7	8			2# washing	Hot water washing	Drying		
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## Comparison Report

**Physical Dimensions dimensions summary:**



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	4.40	5.10	0.173	0.201
B	4.30	4.70	0.169	0.185
C	12.50	14.50	0.492	-
D	1.17	1.37	0.046	0.054
E	0.35	0.55	0.014	0.022
F	1.17	1.37	0.046	0.054
G	0.59	1.40	0.023	0.055
H	0.29	0.51	0.011	0.020
I	3.30	4.10	0.130	0.161

	LSL (mm)	USL (mm)	Items	Before Hang plating process	After Dip soldering process	Result
A	4.40	5.10	MAX	4.65	4.62	Have no difference
			AVG.	4.60	4.58	
			MIN	4.54	4.56	
B	4.30	4.70	MAX	4.59	4.63	
			AVG.	4.55	4.58	
			MIN	4.51	4.55	
C	12.50	14.50	MAX	14.34	14.18	
			AVG.	13.89	13.93	
			MIN	13.75	13.73	
D	1.17	1.37	MAX	1.32	1.31	
			AVG.	1.26	1.26	
			MIN	1.20	1.20	
E	0.35	0.55	MAX	0.44	0.40	
			AVG.	0.39	0.38	
			MIN	0.36	0.36	
F	1.17	1.37	MAX	1.24	1.24	
			AVG.	1.21	1.21	
			MIN	1.18	1.19	
G	0.59	1.40	MAX	1.20	1.20	
			AVG.	1.18	1.17	
			MIN	1.15	1.14	
H	0.29	0.51	MAX	0.37	0.37	
			AVG.	0.34	0.34	
			MIN	0.32	0.32	
I	3.30	4.10	MAX	3.56	3.58	
			AVG.	3.53	3.55	
			MIN	3.52	3.53	

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## Comparison report

**Parametric comparison:**

	ITEM		VCBO(V)	VCEO(V)	VEBO(V)	ICBO(nA)	IEBO(nA)	HFE	Result
	TEST Condition		IC=100uA	IC=10uA	IE=100uA	VCB=30V	VEB=5V	VCE= 5V, IC= 2mA	
	SPEC.		> 50V	> 45V	> 6V	< 15nA	< 100nA	200 < HFE < 450	
Before	Hang plating process	MIN	156.30	77.26	10.82	0.00	0.00	340.30	All meet TSC Spec
		MAX	160.70	79.62	10.87	0.24	0.18	384.00	
		AVG.	157.54	78.90	10.85	0.07	0.08	357.61	
After	Dip soldering process	MIN	155.00	77.84	10.82	0.06	0.00	341.20	
		MAX	157.20	79.82	10.86	0.47	0.45	375.40	
		AVG.	156.27	78.81	10.84	0.23	0.11	354.51	

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## Comparison Report

### Coating Comparison

	Items	Before Hang plating process	After Dip soldering process	Result
Sn(%)	MAX	100	100	Hang plating and dip soldering process have differences in tin layer thickness, but all meet TSC Solderability & Whisker specification.
	AVG.	100	100	
	MIN	100	100	
Sn(um)	Spec	3~20	3~20	
	MAX	9.92	4.49	
	AVG.	8.65	4.04	
	MIN	7.54	3.25	

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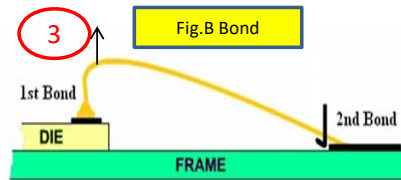
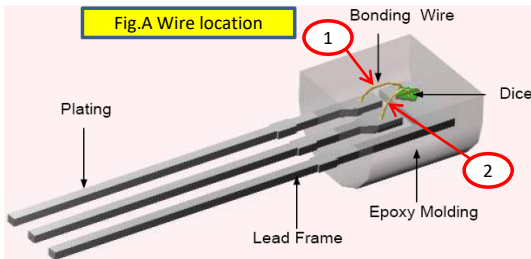
## Comparison Report

**Wire Bond & Die Shear Strength & Wire Bond Shear Comparison**

Unit (gf)

	Location		Sample Size	Count	Before Hang plating process	After Dip soldering process	Spec.	Remark
	Wire 1	bond 3						
Wire Bond Strength  Wire 0.80mil	Wire 1	bond 3	5pcs	MIN	8.978	8.864	≥5g	Have no difference
				MAX	9.566	9.676		
				AVG.	9.238	9.224		
				CPK	7.238	4.981		
	Wire 2	bond 3		MIN	8.584	8.620	≥5g	
				MAX	9.478	9.642		
				AVG.	9.011	9.139		
				CPK	3.714	4.223		
Die Shear Strength	Die		5pcs	MIN	274.860	306.540	≥120g	Have no difference
				MAX	380.580	388.880		
				AVG.	318.784	348.748		
				CPK	1.837	2.264		
Wire Bond Shear  Wire 0.80mil	Wire 1		5pcs	MIN	33.506	34.710	≥17g	Have no difference
				MAX	42.768	41.488		
				AVG.	37.944	38.414		
				CPK	2.231	3.111		
	Wire 2			MIN	36.950	37.900	≥17g	Have no difference
				MAX	43.902	41.460		
				AVG.	40.489	39.816		
				CPK	2.782	6.310		

Location Picture :



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### PCN19001\_Involved P/N list

Family	Package	TSC P/N	New TSC P/N
NPN Bipolar Transistor	TO-92	BC337-16 A1	No Change
NPN Bipolar Transistor	TO-92	BC337-16 A1G	No Change
NPN Bipolar Transistor	TO-92	BC337-16 B1	No Change
NPN Bipolar Transistor	TO-92	BC337-16 B1G	No Change
NPN Bipolar Transistor	TO-92	BC337-16-B0 A1	No Change
NPN Bipolar Transistor	TO-92	BC337-16-B0 A1G	No Change
NPN Bipolar Transistor	TO-92	BC337-16-B0 B1	No Change
NPN Bipolar Transistor	TO-92	BC337-16-B0 B1G	No Change
NPN Bipolar Transistor	TO-92	BC337-25 A1	No Change
NPN Bipolar Transistor	TO-92	BC337-25 B1	No Change
NPN Bipolar Transistor	TO-92	BC337-25 B1G	No Change
NPN Bipolar Transistor	TO-92	BC337-25-B0 A1	No Change
NPN Bipolar Transistor	TO-92	BC337-25-B0 A1G	No Change
NPN Bipolar Transistor	TO-92	BC337-25-B0 B1	No Change
NPN Bipolar Transistor	TO-92	BC337-25-B0 B1G	No Change
NPN Bipolar Transistor	TO-92	BC337-40 A1	No Change
NPN Bipolar Transistor	TO-92	BC337-40 A1G	No Change
NPN Bipolar Transistor	TO-92	BC337-40 B1	No Change
NPN Bipolar Transistor	TO-92	BC337-40 B1G	No Change
NPN Bipolar Transistor	TO-92	BC337-40-B0 A1	No Change
NPN Bipolar Transistor	TO-92	BC337-40-B0 A1G	No Change
NPN Bipolar Transistor	TO-92	BC337-40-B0 B1	No Change
NPN Bipolar Transistor	TO-92	BC337-40-B0 B1G	No Change
NPN Bipolar Transistor	TO-92	BC338-16 A1	No Change
NPN Bipolar Transistor	TO-92	BC338-16 A1G	No Change
NPN Bipolar Transistor	TO-92	BC338-16 B1	No Change
NPN Bipolar Transistor	TO-92	BC338-16 B1G	No Change
NPN Bipolar Transistor	TO-92	BC338-16-B0 A1	No Change
NPN Bipolar Transistor	TO-92	BC338-16-B0 A1G	No Change
NPN Bipolar Transistor	TO-92	BC338-16-B0 B1	No Change
NPN Bipolar Transistor	TO-92	BC338-16-B0 B1G	No Change
NPN Bipolar Transistor	TO-92	BC338-25 A1	No Change
NPN Bipolar Transistor	TO-92	BC338-25 A1G	No Change
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NPN Bipolar Transistor	TO-92	BC338-25 B1G	No Change
NPN Bipolar Transistor	TO-92	BC338-25-B0 A1	No Change
NPN Bipolar Transistor	TO-92	BC338-25-B0 A1G	No Change
NPN Bipolar Transistor	TO-92	BC338-25-B0 B1	No Change
NPN Bipolar Transistor	TO-92	BC338-25-B0 B1G	No Change
NPN Bipolar Transistor	TO-92	BC338-40 A1	No Change
NPN Bipolar Transistor	TO-92	BC338-40 A1G	No Change
NPN Bipolar Transistor	TO-92	BC338-40 B1	No Change
NPN Bipolar Transistor	TO-92	BC338-40 B1G	No Change
NPN Bipolar Transistor	TO-92	BC338-40-B0 A1	No Change
NPN Bipolar Transistor	TO-92	BC338-40-B0 A1G	No Change
NPN Bipolar Transistor	TO-92	BC338-40-B0 B1	No Change
NPN Bipolar Transistor	TO-92	BC338-40-B0 B1G	No Change
NPN Bipolar Transistor	TO-92	BC546A A1	No Change
NPN Bipolar Transistor	TO-92	BC546A A1G	No Change
NPN Bipolar Transistor	TO-92	BC546A B1	No Change
NPN Bipolar Transistor	TO-92	BC546A B1G	No Change
NPN Bipolar Transistor	TO-92	BC546B A1	No Change
NPN Bipolar Transistor	TO-92	BC546B A1G	No Change
NPN Bipolar Transistor	TO-92	BC546B B1	No Change
NPN Bipolar Transistor	TO-92	BC546B B1G	No Change
NPN Bipolar Transistor	TO-92	BC546C A1	No Change
NPN Bipolar Transistor	TO-92	BC546C A1G	No Change
NPN Bipolar Transistor	TO-92	BC546C B1	No Change
NPN Bipolar Transistor	TO-92	BC546C B1G	No Change
NPN Bipolar Transistor	TO-92	BC547A A1	No Change
NPN Bipolar Transistor	TO-92	BC547A A1G	No Change
NPN Bipolar Transistor	TO-92	BC547A B1	No Change
NPN Bipolar Transistor	TO-92	BC547A B1G	No Change
NPN Bipolar Transistor	TO-92	BC547B A1	No Change



Thyristor	TO-92	MCR100-7 A1	No Change
Thyristor	TO-92	MCR100-7 A1G	No Change
Thyristor	TO-92	MCR100-7 B1	No Change
Thyristor	TO-92	MCR100-7 B1G	No Change
Thyristor	TO-92	MCR100-8 A1	No Change
Thyristor	TO-92	MCR100-8 A1G	No Change
Thyristor	TO-92	MCR100-8 B1	No Change
Thyristor	TO-92	MCR100-8 B1G	No Change

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